

## 1 310 nm FOR 156 Mb/s, 622 Mb/s, 1.25 Gb/s

## InGaAsP MQW-FP LASER DIODE

### DESCRIPTION

The NX5304 Series is a 1 310 nm Multiple Quantum Well (MQW) structured Fabry-Perot (FP) laser diodes with InGaAs monitor PIN-PD. These devices are designed for 156 Mb/s: STM-1 (I-1, S-1.1, L-1.1), 622 Mb/s: STM-4 (I-4, S-4.1), Gigabit Ethernet application and ideal for Synchronous Digital Hierarchy (SDH) system.

### FEATURES

- Optical output power  $P_o = 5.0 \text{ mW}$
- Low threshold current  $I_{th} = 10 \text{ mA}$
- High speed  $t_r = 0.3 \text{ ns MAX.}$   
 $t_f = 0.3 \text{ ns MAX.}$
- Wide operating temperature range  $T_c = -40 \text{ to } +85^\circ\text{C}$
- InGaAs monitor PIN-PD
- CAN package  $\phi 5.6 \text{ mm}$
- Fiber coupling point  $5.8 \text{ mm}$
- Based on Telcordia reliability



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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

**Top View:** Shows a circular package with a central fiber coupling point. Dimensions include a total diameter of  $\phi 5.6^{+0.00}_{-0.03}$ , an inner diameter of  $\phi 4.2 \pm 0.1$ , and a coupling point diameter of  $\phi 3.55 \pm 0.1$ . The coupling point is offset by  $1.0 \pm 0.1$  mm from the center. The angle between the coupling point and the center is  $110^\circ \pm 2^\circ$ . The coupling point is located at a distance of  $0.3^{+0.1}_{-0.0}$  mm from the center.

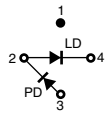

**Bottom View:** Shows the package from the bottom, with a central fiber coupling point and four pins labeled 1, 2, 3, and 4. The coupling point is located at a distance of  $0.3^{+0.1}_{-0.0}$  mm from the center.

**Pin Connections:** The package has four pins: 1 (Case), 2 (LD), 3 (PD), and 4 (LD). The connections are as follows: Pin 1 is connected to Pin 2 (LD) and Pin 4 (LD). Pin 3 (PD) is connected to Pin 2 (LD) and Pin 4 (LD).

**Reference Plane:** The reference plane is located at a distance of  $5.80 \pm 0.05$  mm from the bottom of the package. The distance from the reference plane to the top of the package is  $3.87 \pm 0.3$  mm. The distance from the reference plane to the bottom of the package is  $15.0 \pm 1.0$  mm. The distance from the reference plane to the center of the package is  $2.97 \pm 0.2$  mm. The distance from the reference plane to the center of the package is  $2.97 \pm 0.2$  mm. The distance from the reference plane to the center of the package is  $2.97 \pm 0.2$  mm.

**\*1 Recommendation of Fiber Coupling Conditions**  
 Fiber : SMF with 8 degree angle-polished ferrule  
 Fiber coupling distance :  $5.80 \pm 0.05$  mm from reference plane.  
 Fiber coupling alignment : optimized x, y,  $\theta$  ( $\Delta x, \Delta y \leq \pm 300 \mu\text{m}$ ).

ORDERING INFORMATION

Part Number	Package	Pin Connections
NX5304EH	4-pin CAN with ball lens cap	
NX5304EK		

- Remarks**
- 1. The color of ball lens cap might be observed differently from our can package products.
  - 2. The hermetic test will be performed as AQL 1.0%.

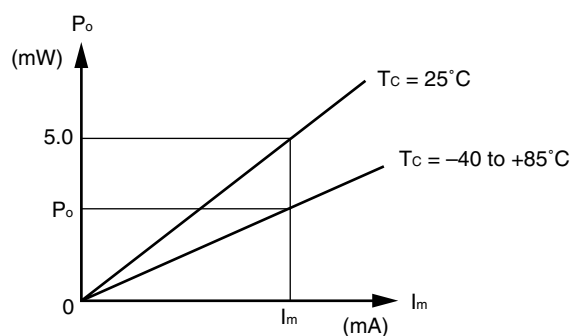
**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Ratings	Unit
Optical Output Power	$P_o$	10	mW
Forward Current of LD	$I_F$	150	mA
Reverse Voltage of LD	$V_R$	2.0	V
Forward Current of PD	$I_F$	10	mA
Reverse Voltage of PD	$V_R$	20	V
Operating Case Temperature	$T_C$	-40 to +85	°C
Storage Temperature	$T_{stg}$	-40 to +85	°C
Assembly Temperature	$T_{asb}$	150 (15 Hr)	°C
Lead Soldering Temperature	$T_{sld}$	350 (3 sec.)	°C
Relative Humidity (noncondensing)	RH	85	%

**ELECTRO-OPTICAL CHARACTERISTICS (T<sub>c</sub> = 25°C, unless otherwise specified)**

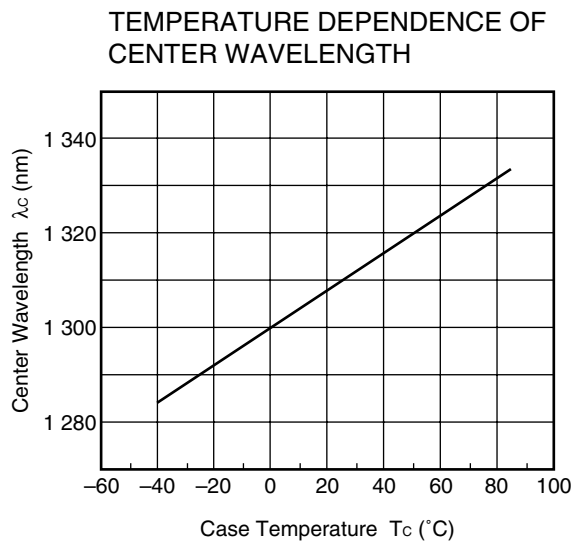
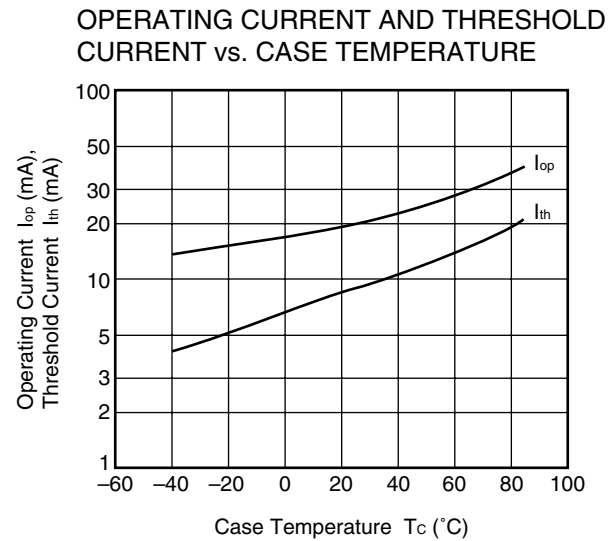
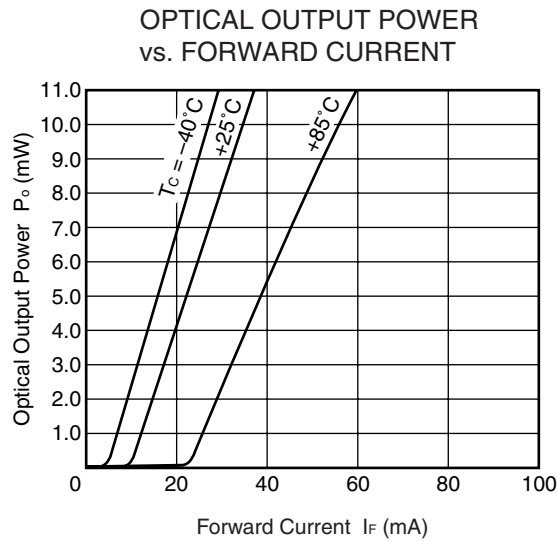
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Operating Voltage	V <sub>op</sub>	P <sub>o</sub> = 5.0 mW, T <sub>c</sub> = -40 to +85°C		1.1	1.5	V
Threshold Current	I <sub>th</sub>			10	15	mA
		T <sub>c</sub> = 85°C		25	30	
Threshold Output Power	P <sub>th</sub>	T <sub>c</sub> = -40 to +85°C, I <sub>F</sub> = I <sub>th</sub>		100	200	μW
Differential Efficiency	η <sub>d</sub>		0.32	0.4		W/A
Temperature Dependence of Differential Efficiency	Δη <sub>d</sub>	Δη <sub>d</sub> = 10 log $\frac{\eta_d (@ 85^\circ\text{C})}{\eta_d (@ 25^\circ\text{C})}$	-3.0	-1.2		dB
Center Wavelength	λ <sub>c</sub>	P <sub>o</sub> = 5.0 mW, RMS (-20 dB) T <sub>c</sub> = -40 to +85°C	1 263		1 360	nm
Temperature Dependence of Center Wavelength	Δλ/ΔT	T <sub>c</sub> = -40 to +85°C		0.4	0.5	nm/°C
Spectral Width	σ	P <sub>o</sub> = 5.0 mW, RMS (-20 dB) T <sub>c</sub> = -40 to +85°C		1.0	2.5	nm
Rise Time	t <sub>r</sub>	10-90%		0.15	0.3	ns
Fall Time	t <sub>f</sub>	90-10%		0.15	0.3	ns
Monitor Current	I <sub>m</sub>	V <sub>R</sub> = 5 V, P <sub>o</sub> = 5.0 mW	200	500	800	μA
Monitor Dark Current	I <sub>D</sub>	V <sub>R</sub> = 5 V		0.1	10	nA
		V <sub>R</sub> = 5 V, T <sub>c</sub> = -40 to +85°C			500	
Monitor PD Terminal Capacitance	C <sub>t</sub>	V <sub>R</sub> = 5 V, f = 1 MHz		6	20	pF
Tracking Error <sup>*1</sup>	γ	I <sub>m</sub> = const. (@ P <sub>o</sub> = 5.0 mW, T <sub>c</sub> = 25°C) T <sub>c</sub> = -40 to +85°C	-1.0		1.0	dB

\*1 Tracking Error: γ



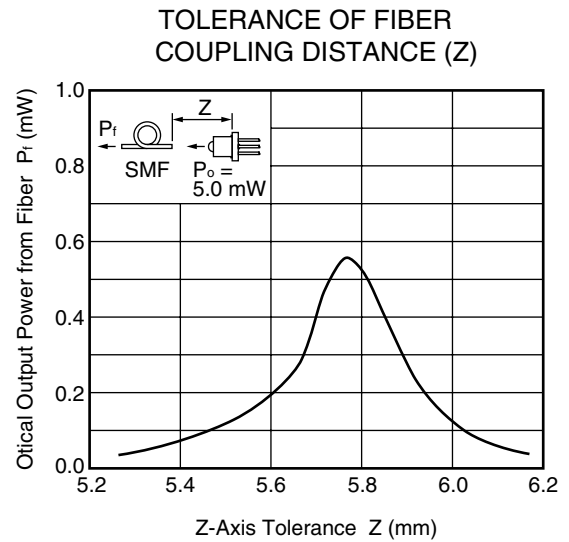
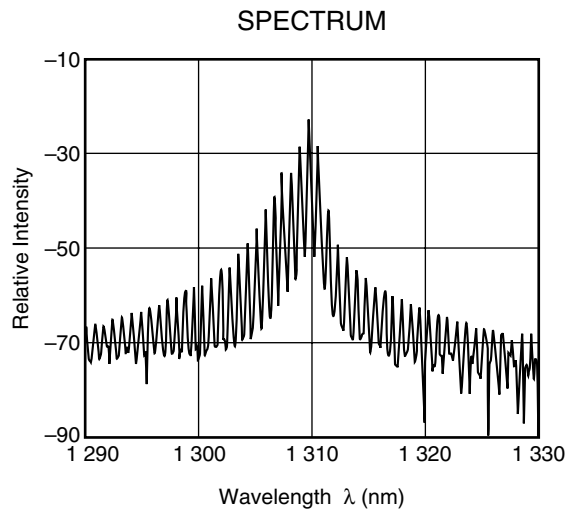
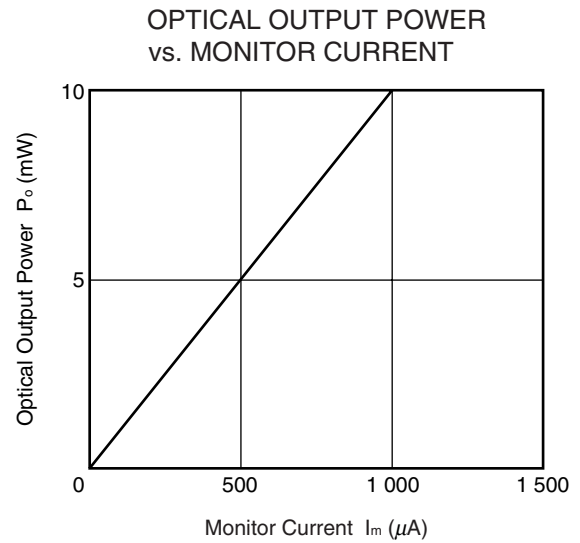
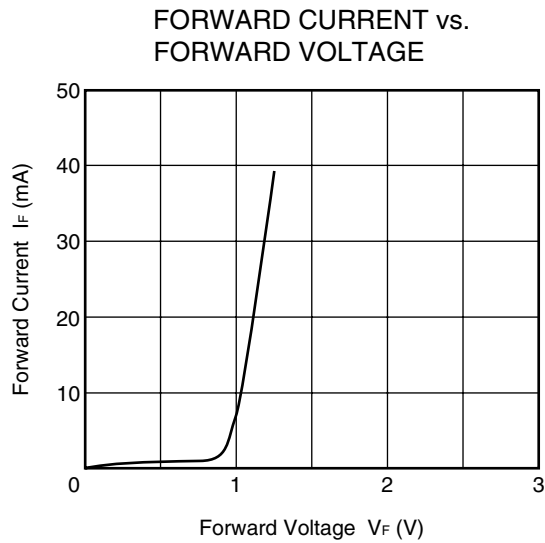
$$\gamma = \left| 10 \log \frac{P_o}{5.0} \right| [\text{dB}]$$

★ TYPICAL CHARACTERISTICS ( $T_c = -40$  to  $+85^\circ\text{C}$ , unless otherwise specified)



**Remark** The graphs indicate nominal characteristics.

★ TYPICAL CHARACTERISTICS ( $T_c = 25^\circ\text{C}$ , unless otherwise specified)



**Remark** The graphs indicate nominal characteristics.

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Part Number	Absolute Maximum Ratings		Electro-Optical Characteristics (T <sub>c</sub> = 25°C)				Application	Package
	T <sub>c</sub> (°C)	T <sub>stg</sub> (°C)	I <sub>th</sub> (mA)	P <sub>o</sub> (mW)	λ (nm)			
			TYP.	TYP.	MIN.	MAX.		
NX5304 Series	−40 to +85	−40 to +85	10	5	1 263	1 360	156 Mb/s: STM-1 (I-1, S-1.1, L-1.1)	CAN
							622 Mb/s: STM-4 (I-4, S-4.1)	
							1.25 Gb/s: GbE	
NX5306 Series	−40 to +85	−40 to +85	10	5	1 263	1 360	156 Mb/s: STM-1 (I-1, S-1.1, L-1.1)	CAN
							622 Mb/s: STM-4 (I-4, S-4.1)	
							1.25 Gb/s: GbE	
NX5307 Series	−40 to +85	−40 to +85	10	10	1 266	1 360	2.5 Gb/s: STM-16	CAN
NX5501 Series	−20 to +85	−40 to +85	8	5	1 480	1 580	For FTTH	CAN
NX5504 Series	−20 to +85	−40 to +85	8	5	1 480	1 580	For FTTH	CAN
NX6306 Series	−40 to +85	−40 to +85	10	5	1 280	1 335	156 Mb/s: STM-1 (I-1, S-1.1, L-1.1)	CAN
							622 Mb/s: STM-4 (I-4, S-4.1, L-4.1)	
							1.25 Gb/s: GbE	
NX6307 Series	−20 to +85	−40 to +85	10	7	1 280	1 335	2.5 Gb/s: STM-16 (S-16.1, L-16.1)	CAN
NX6504 Series	−10 to +85	−40 to +85	12	5	1 530	1 570	156 Mb/s: STM-1	CAN
							622 Mb/s: STM-4	
NX6508 Series	0 to +70	−40 to +85	10	5	λ <sub>p</sub> −3 <sup>*1</sup>	λ <sub>p</sub> +3 <sup>*1</sup>	For CWDM	CAN
NX6509 Series	−20 to +85	−40 to +85	10	5	1 530	1 570	2.5 Gb/s: STM-16 (L-16.2)	CAN

\*1 λ<sub>p</sub> = 1 470, 1 490, 1 510, 1 530, 1 550, 1 570, 1 590, 1 610 nm



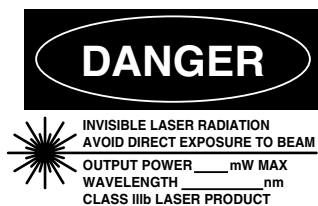
**REFERENCE**

Document Name	Document No.
OPTICAL SEMICONDUCTOR DEVICES FOR FIBEROPTIC COMMUNICATIONS SELECTION GUIDE	PL10161E
Opto-Electronics Devices Pamphlet	PX10160E

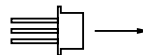
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SAFETY INFORMATION ON THIS PRODUCT



SEMICONDUCTOR LASER



AVOID EXPOSURE-Invisible  
Laser Radiation is emitted from  
this aperture

<b>Warning</b> Laser Beam	<p>A laser beam is emitted from this diode during operation. The laser beam, visible or invisible, directly or indirectly, may cause injury to the eye or loss of eyesight.</p> <ul style="list-style-type: none"> <li>• Do not look directly into the laser beam.</li> <li>• Avoid exposure to the laser beam, any reflected or collimated beam.</li> </ul>
<b>Caution</b> GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.             <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>

► For further information, please contact

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